

Transmission Electron Microscopy of Semiconductors and Heterostructures

D. Cherns

University of Bristol, UK

Outline

- Background
- Scattering theory
- Applications
 - Imaging (defects, interfaces, atomic structure ...)
 - Diffraction (strain, polarity ...)
 - Microanalysis (chemical composition etc)
- Recent developments

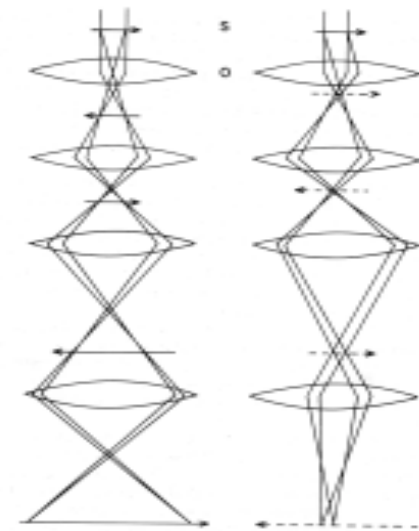
Transmission electron microscope (TEM)

- Heated W, LaB6 or field emission source
- Electromagnetic lenses, giving **direct imaging or diffraction using a parallel probe, or microanalysis using a focused probe**
- Thin samples (10- 500 nm)



Hitachi HF2000 TEM

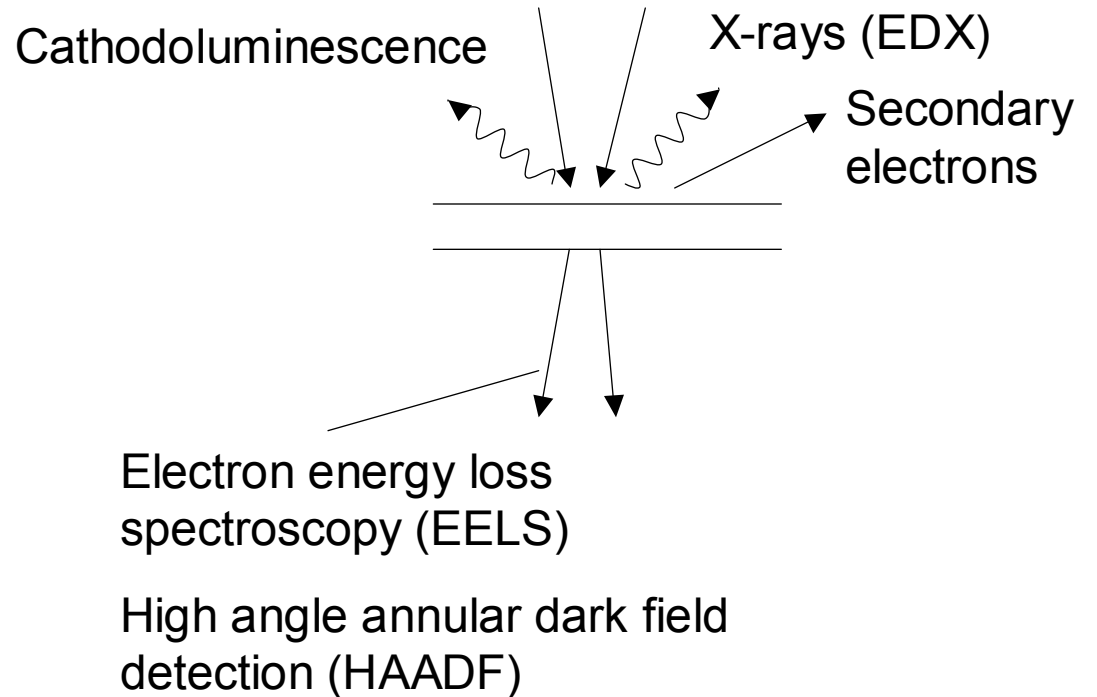
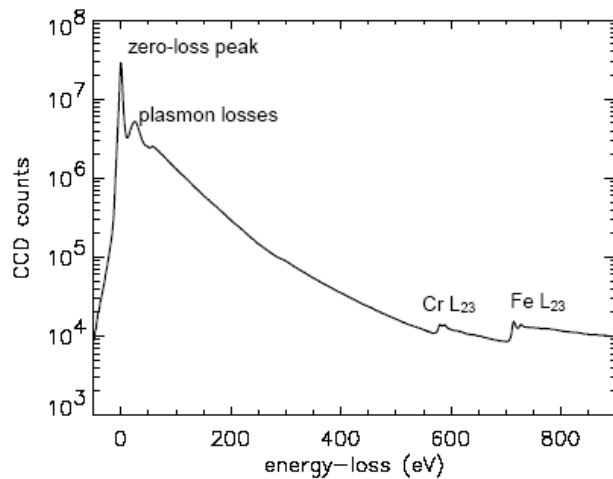
Imaging
and
diffraction!



Electrons as particles (200kV)

- Electrons travel at $0.7c$ (relativistic)
- Up to 10^{10} e/sec. Focused probe (field emission gun) can generate up to 1nA into 1nm probe, or greater than 10^8 e/atom/sec
- An electron can transfer up to 44eV to a carbon atom in a head-on collision. This can generate point defects (bulk) and sputtering (surface)
- Less energetic collisions generate phonons, excitation of inner and outer shell electrons, plasmons and photons. This inelastic scattering gives microanalysis and imaging using a variety of signals
- Radiation damage can be a problem, with some organic materials damaging at down to 1 e/atom. Conversely there is potential for lithography and hole drilling

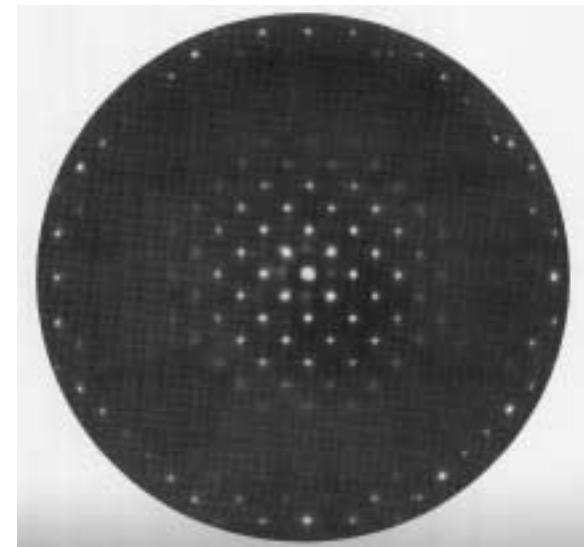
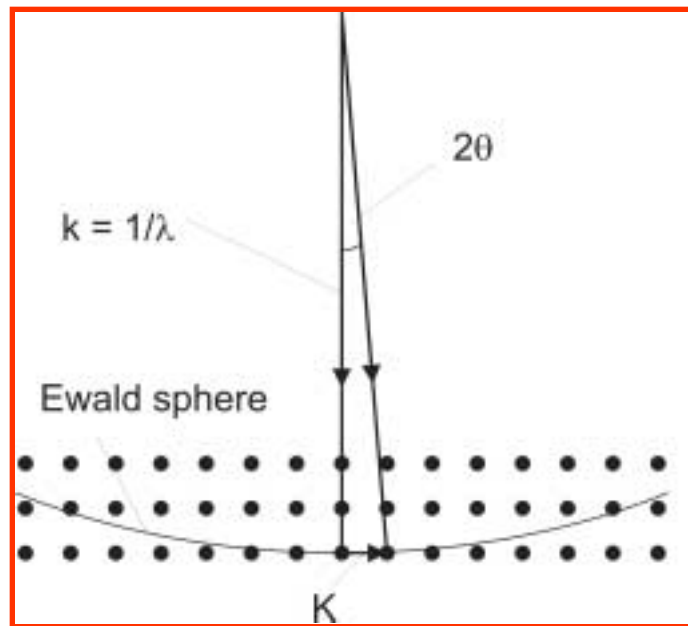
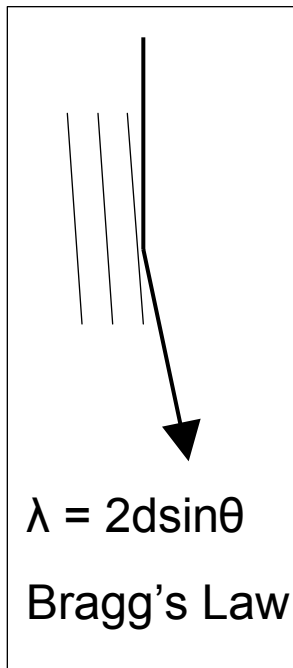
Inelastic scattering: some useful signals



Electrons as waves: diffraction

$\lambda = h/p$ (de Broglie) = 0.0025nm (200kV)

c.f. $\lambda = 0.1$ nm (X-rays), 500nm (light)



$\sim 5^\circ$

Spatial resolution

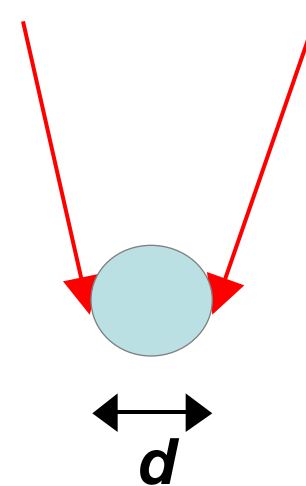
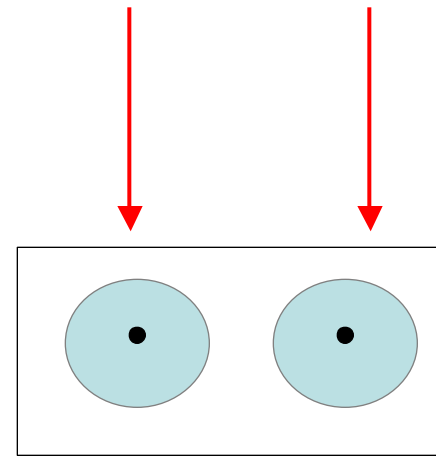
$$d = \lambda / \alpha$$

Abbe criterion ($\alpha = \text{convergence angle}$)

Light microscope: $\alpha \sim 1 \text{ rad}$, $d \sim \lambda$

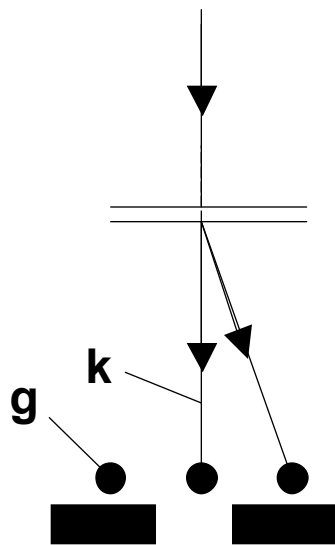
TEM: $\alpha \sim 10^{-2} \text{ rad}$, $d \sim 100\lambda$ (0.2nm!)

i.e. resolution is comparable to
atom spacings, and α is
comparable to the Bragg angle

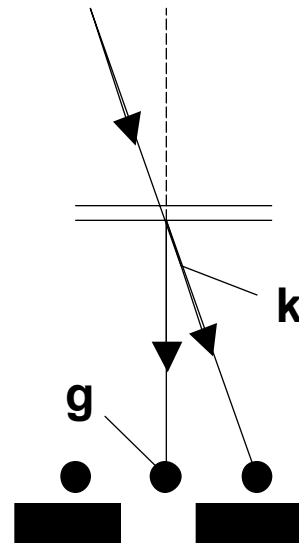


Imaging modes

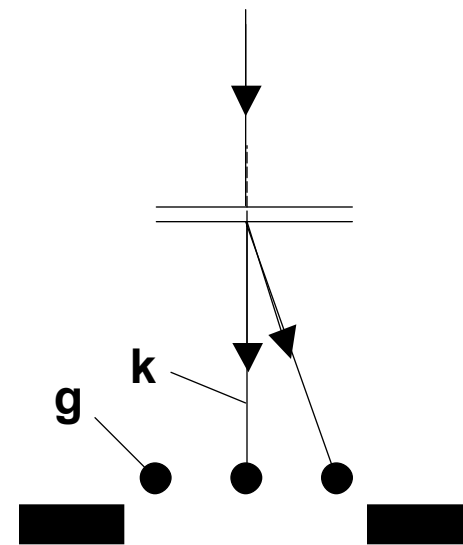
The presence of aberrations requires that imaged beams must be as close as possible to the optic axis. Selection is by means of an objective aperture



Bright field



Dark field



Lattice imaging

Scattering theory

Amplitude scattered into g (thin crystal limit):

$$\frac{d\varphi_g}{\varphi_0} = i\pi\Delta t / \xi_g$$

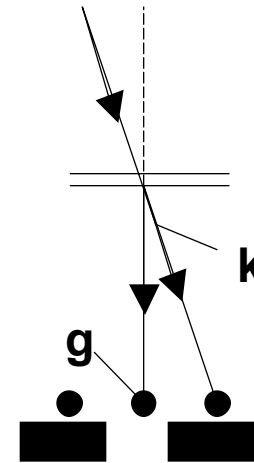
Δt = specimen thickness

Φ = amplitude

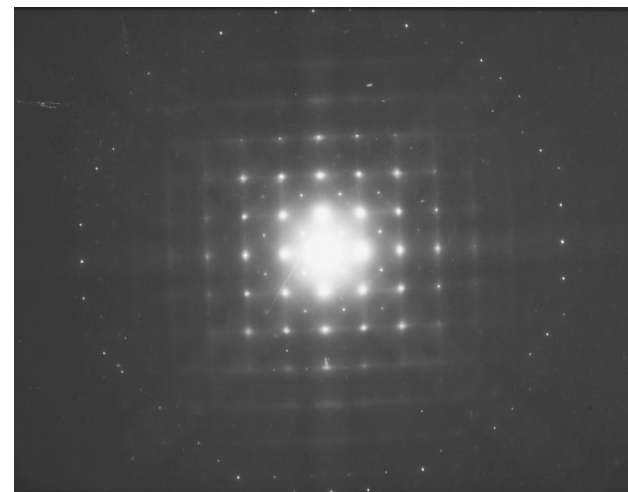
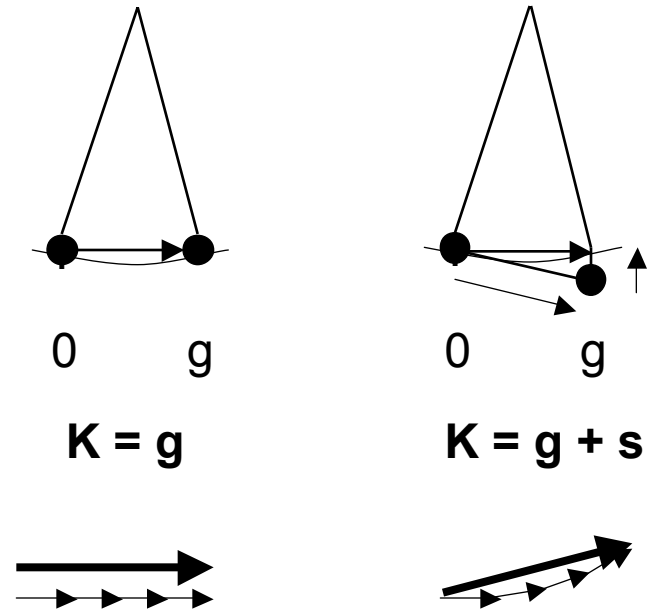
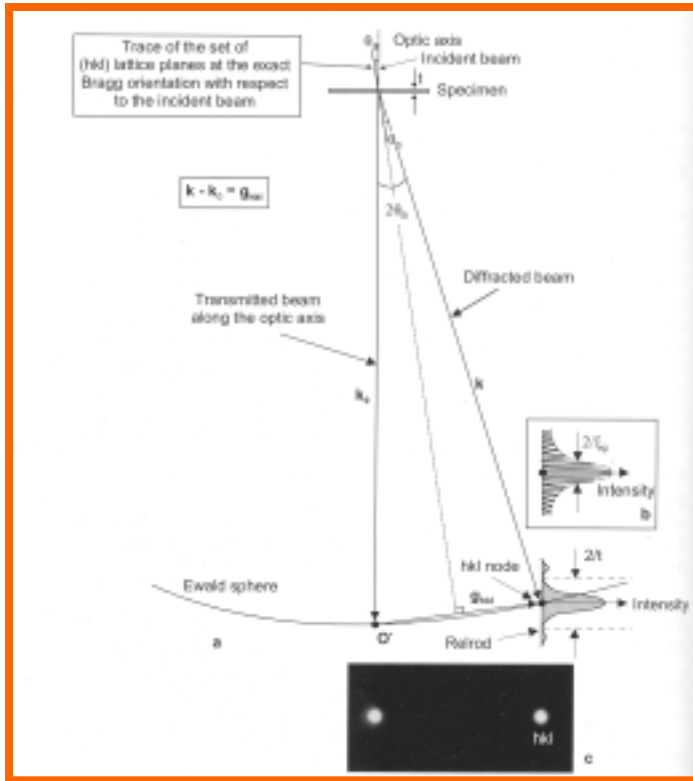
ξ_g = extinction distance

For electrons, $\xi_g \sim 10 - 100$ nm

For X-rays, $\xi_g \sim 2-3$ orders of magnitude greater



TEM: why so many reflections?

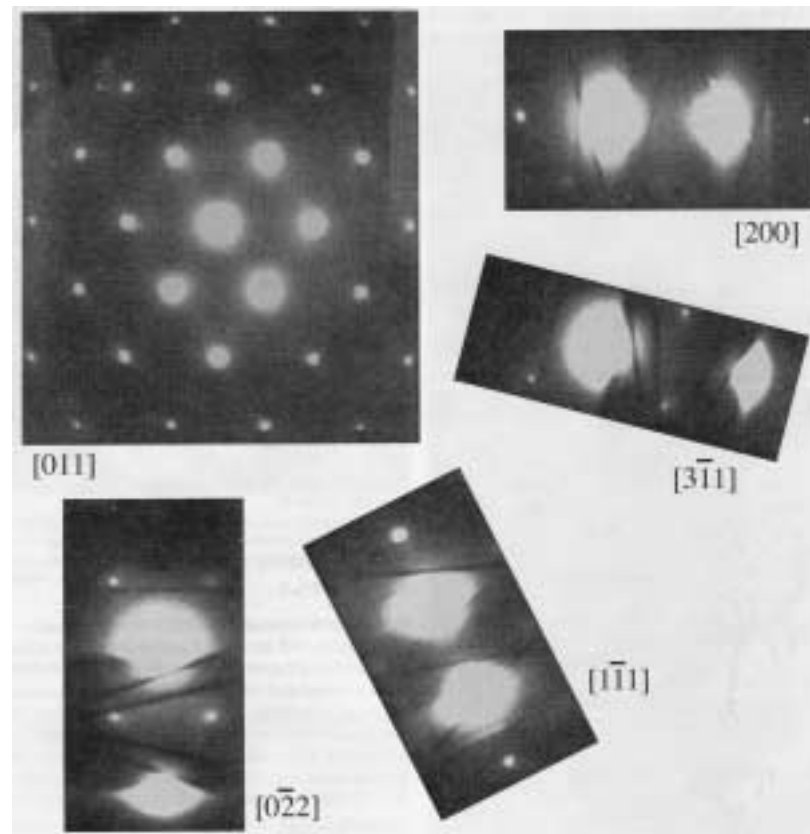


Two-beam imaging

In general, electron diffraction is a **many beam problem**

Fortunately, it is possible to orient a single crystal sample until **only one diffracted beam is strong**.

Understanding diffraction is then a relatively simple two-beam problem:



Two-beam imaging: significance of “deviation parameter” s

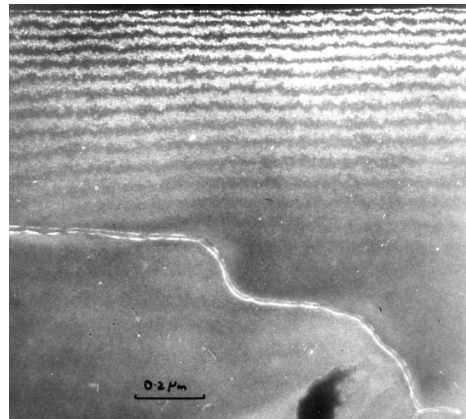
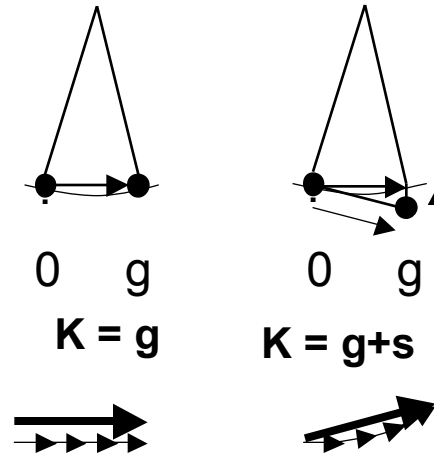
Large s is simple (kinematical):

$$\frac{\phi_g}{\phi_0} = \frac{i\pi}{\xi_s} \int_t^0 \exp(-2\pi i s z) dz$$

$$\frac{\phi_g^2}{\phi_0^2} = \frac{\pi^2}{\xi_s^2} \frac{\sin^2(\pi t s)}{(\pi s)^2}$$

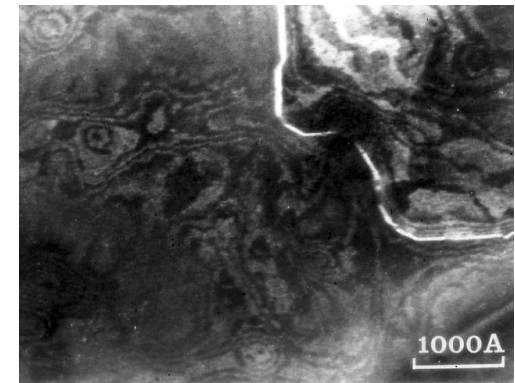
$$\Delta t = \frac{1}{s}$$

?



$s = 0$

$s = 0.2 \text{ nm}^{-1}$



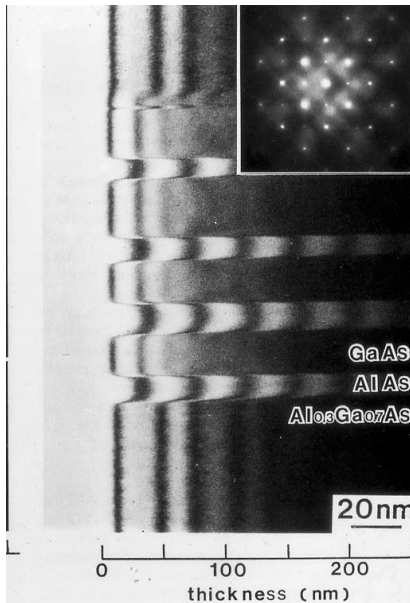
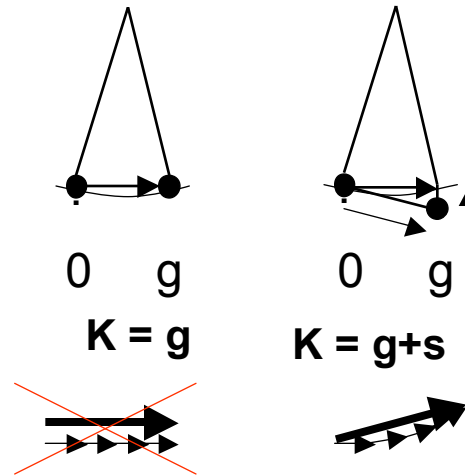
$s = 1.3 \text{ nm}^{-1}$
(surface steps)

Two-beam imaging: significance of “deviation parameter” s

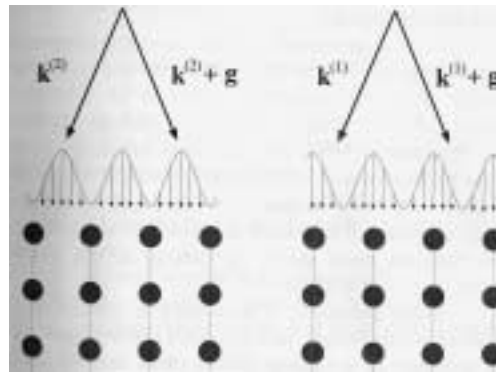
$s = 0$: behaviour is dynamical:

$$\frac{\phi_g^2}{\phi_0^2} = \frac{\pi^2}{\xi_g^2} \frac{\sin^2 \pi \sqrt{s^2 + \xi_g^{-2}}}{\pi^2 (s^2 + \xi_g^{-2})}$$

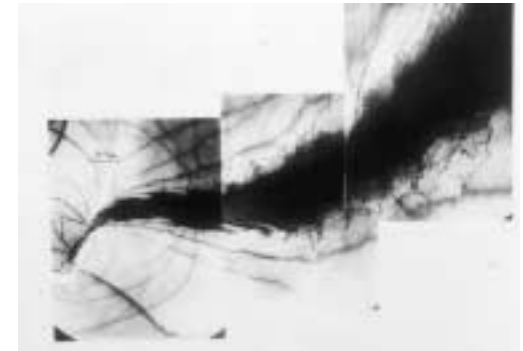
$$\Delta t = 1 / \sqrt{s^2 + \xi_g^{-2}}$$



$s = 0, \Delta t = 1/s = \xi_g$



Bloch waves



Channelling

Two-beam imaging: defects

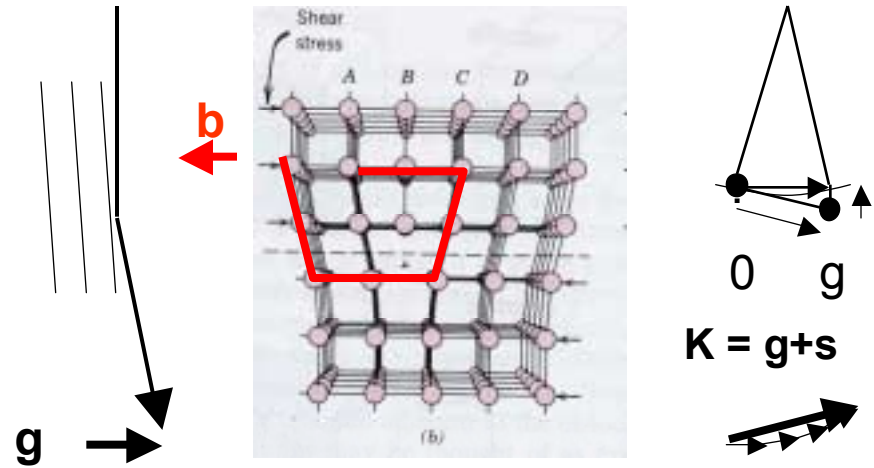
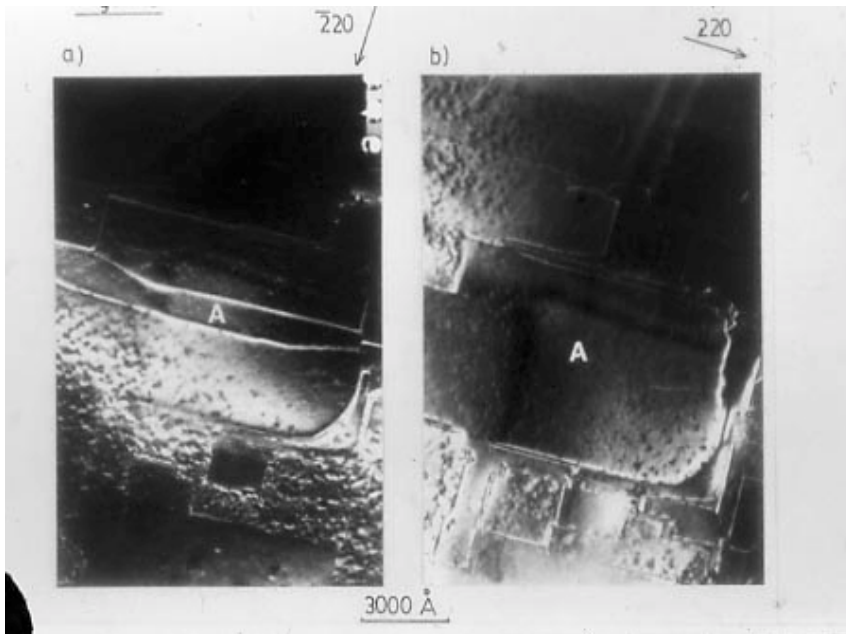
A good qualitative understanding of contrast can be obtained using the kinematical formula

$$\frac{\phi_g}{\phi_0} = \frac{i\pi}{\xi_g} \int_t^0 \exp(-2\pi i(sz + \underline{g} \cdot \underline{R})) dz$$

e.g. for dislocations $\underline{g} \cdot \underline{R}$ defines bending of diffracting planes

Two-beam imaging: defects

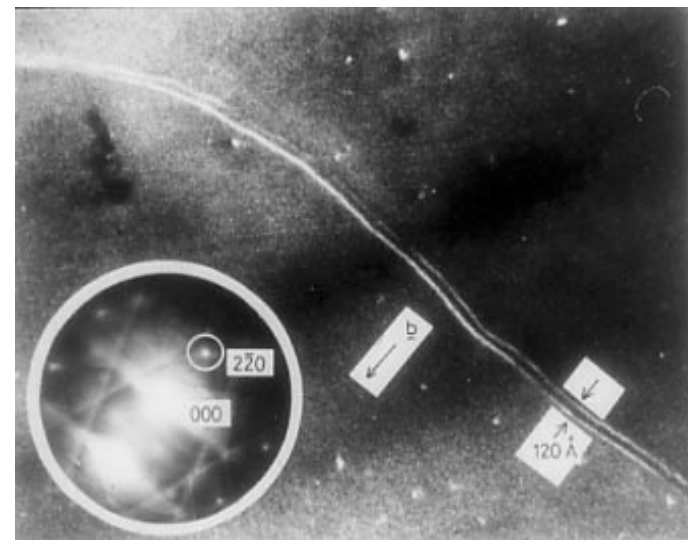
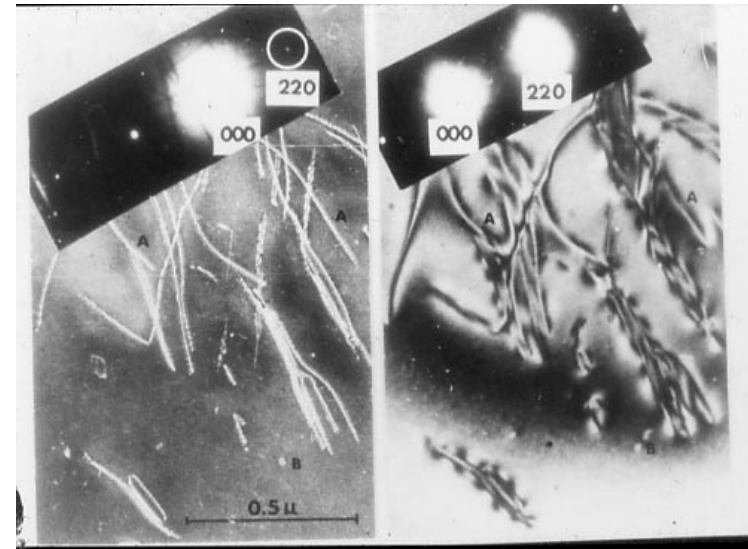
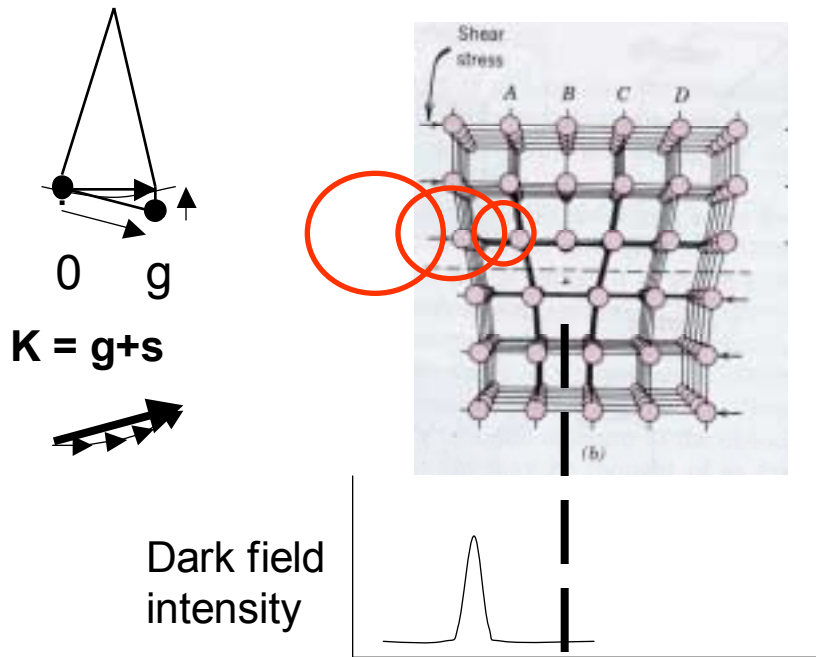
Dislocations are seen when the diffracting planes are distorted, i.e. when the dot product $\mathbf{g} \cdot \mathbf{b}$ is non-zero



Analysis of misfit dislocations in $\text{NiSi}_2/(001)\text{Si}$ interface

Core structure of dislocations: weak beam technique

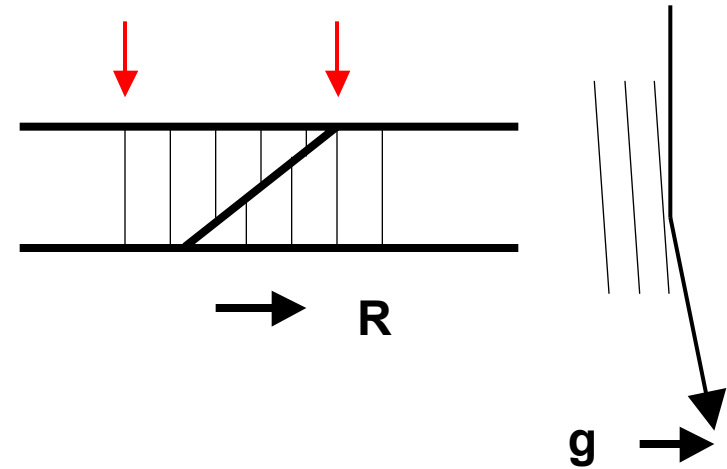
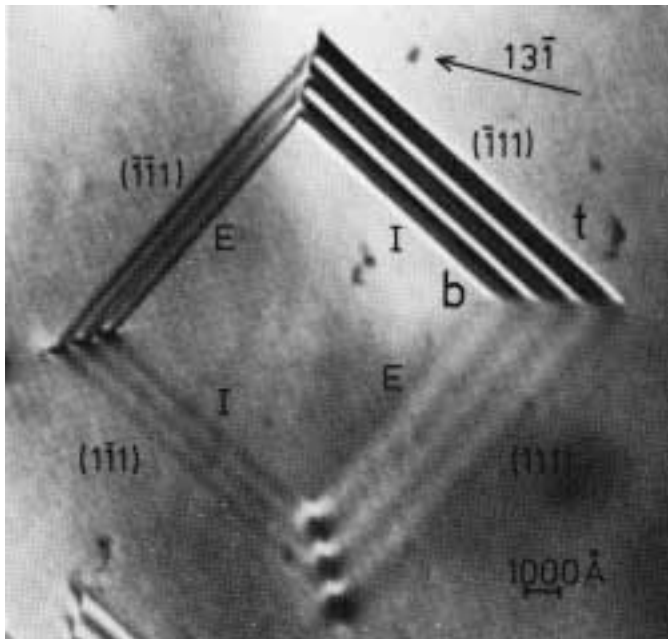
Image is seen where planes are bent towards $s = 0$, i.e. progressively closer to the core as s increases



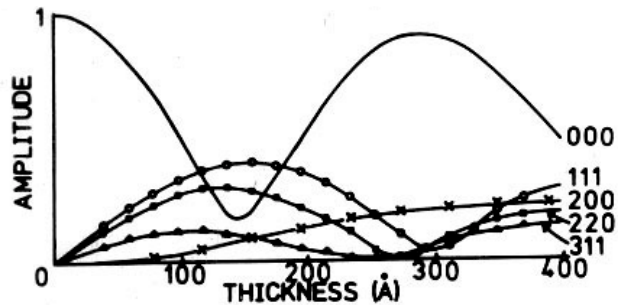
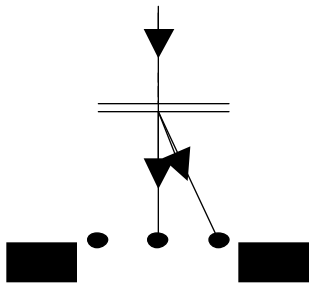
Dislocations in semiconductors are often dissociated

Two-beam imaging: defects

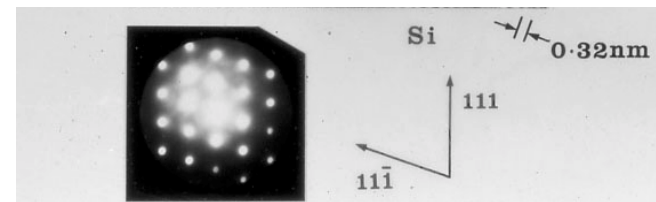
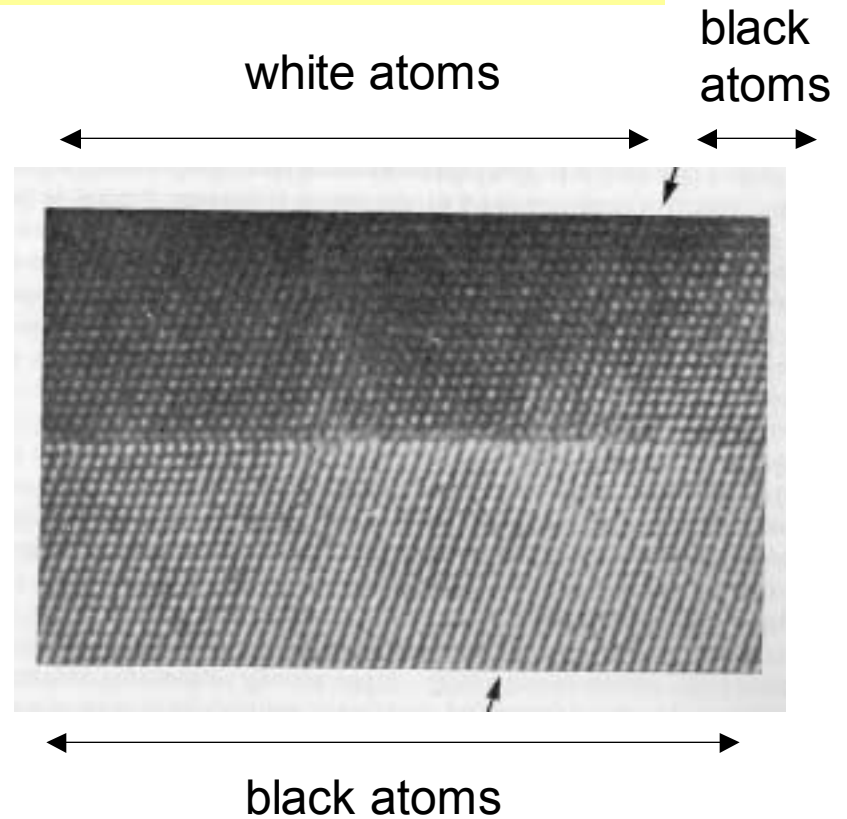
Stacking faults are visible when the diffracting planes are fractionally displaced, i.e. contrast depends on $g \cdot R$



Lattice imaging: many (strong) beams



Scattered amplitudes from Si viewed along [110] as a function of film thickness. Phases vary also!



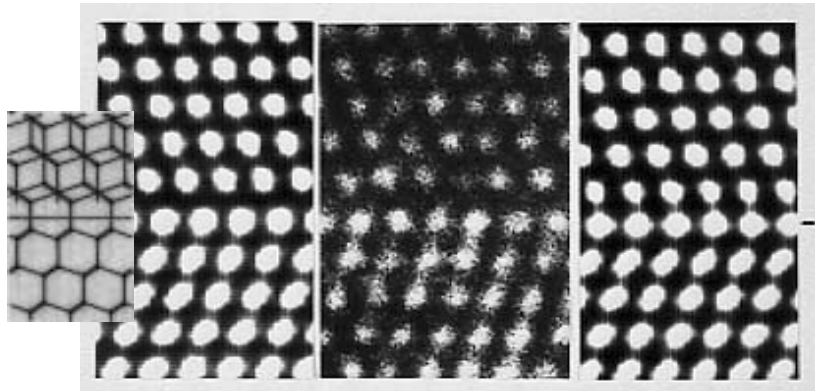
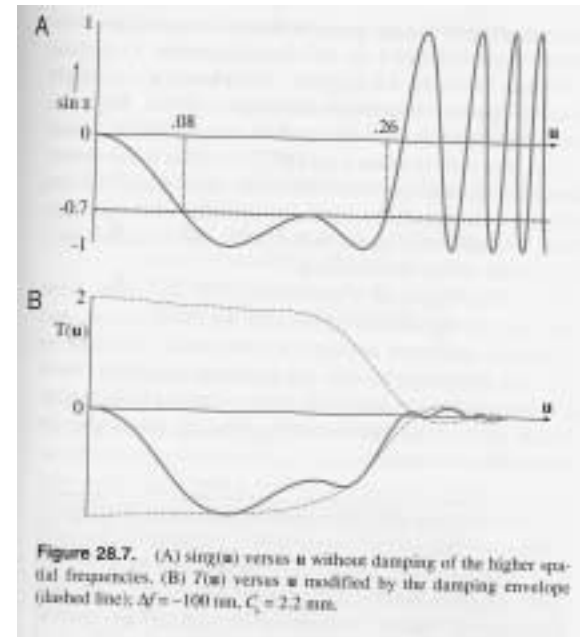
NiSi₂/(111)Si

Can we believe what we see?

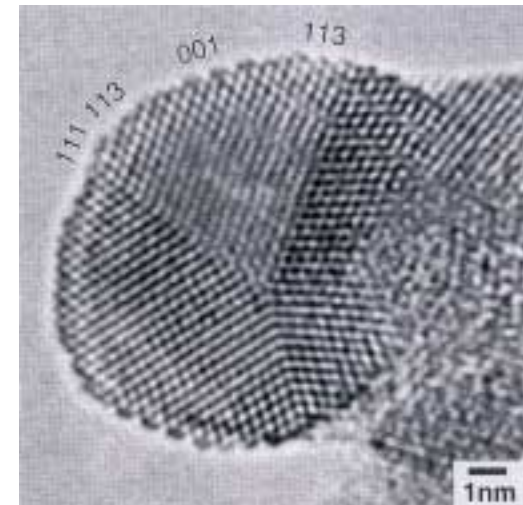
Lattice imaging

Hence two problems:

- Seeing is not believing
- Limited resolution described by the contrast transfer function
- However, with computation many problems can be solved



“B” NiSi₂/(111)Si along [110]



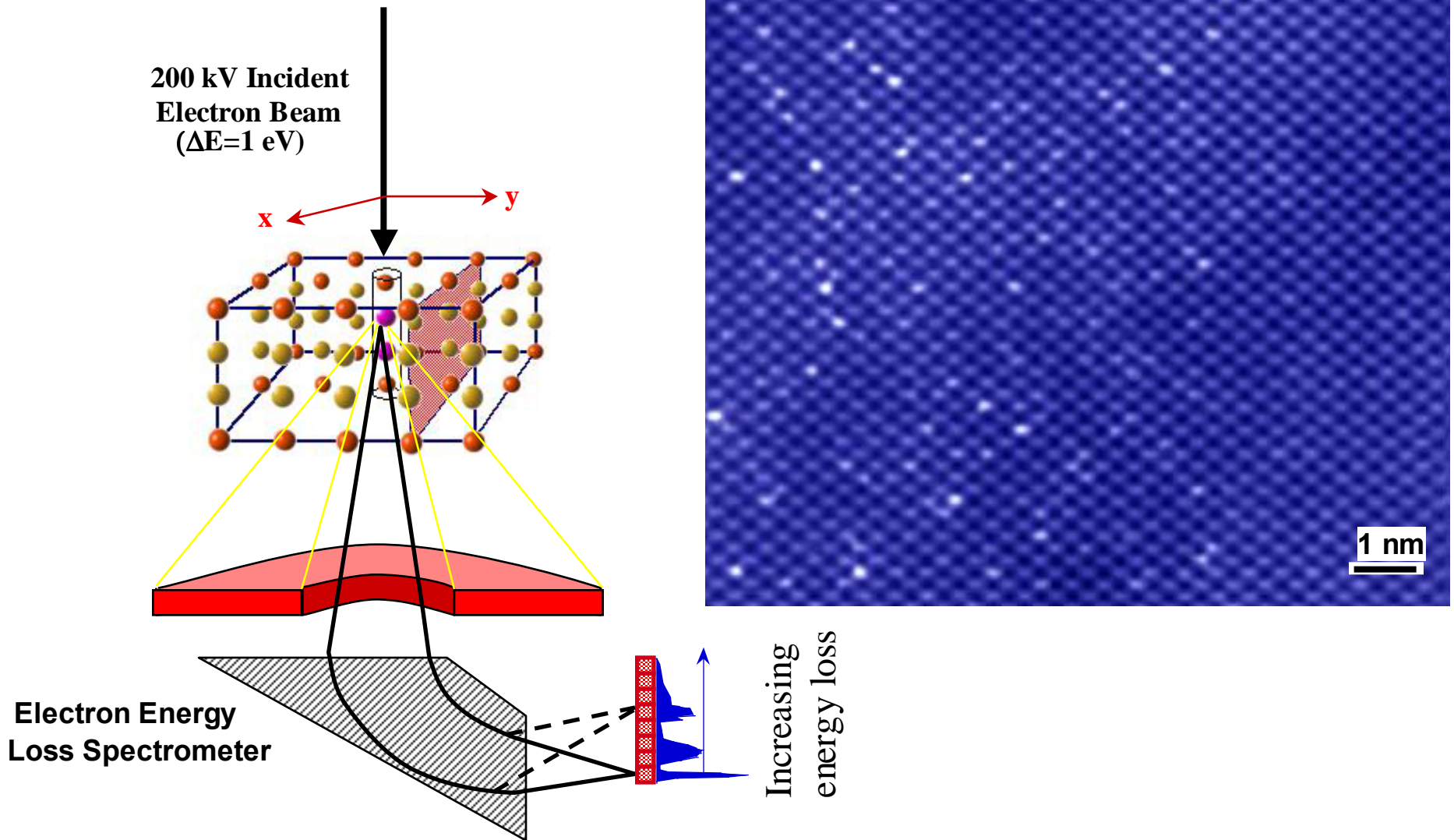
Si nanocrystal (Takeguchi JEM 48, 1087)

Lattice imaging

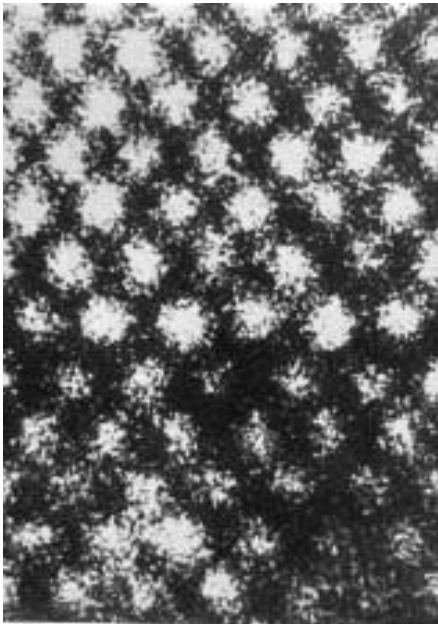
Current advances:

- Resolution improvements from 0.2nm to better than 0.1nm through aberration correction
- Smaller focused probes
- Improved resolution of structure (e.g closely spaced atoms in semiconductors), lattice imaging by scanning TEM (STEM) using chemically sensitive signals

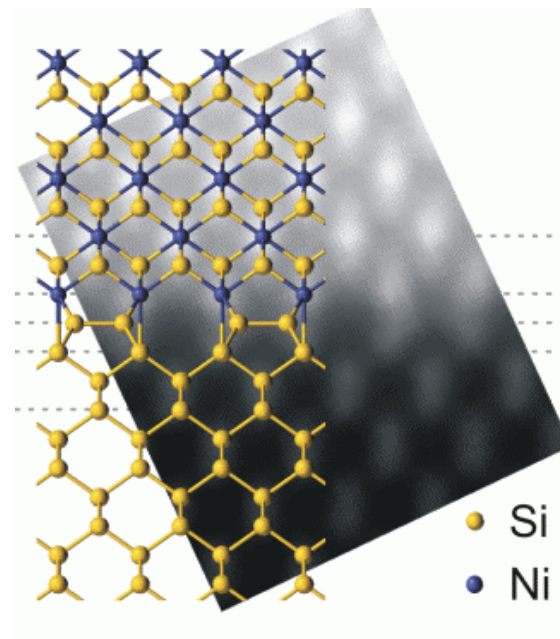
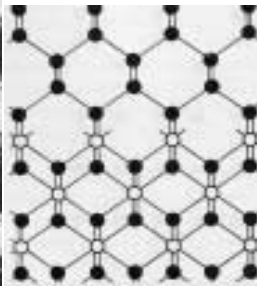
HAADF: Sb dopants in Si
(courtesy of D. Muller)



NiSi₂/(001)Si 1984 - 2004

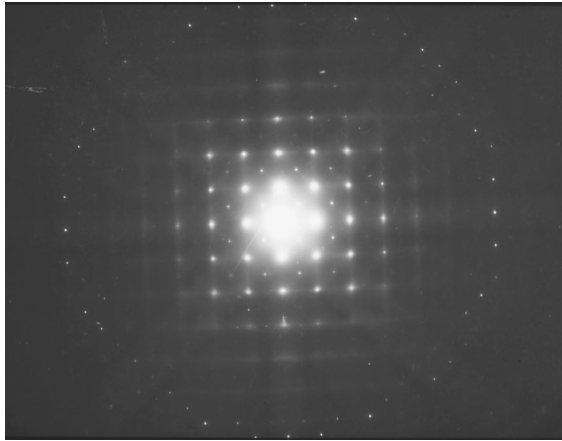


Direct image

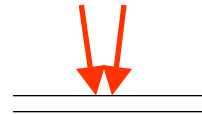
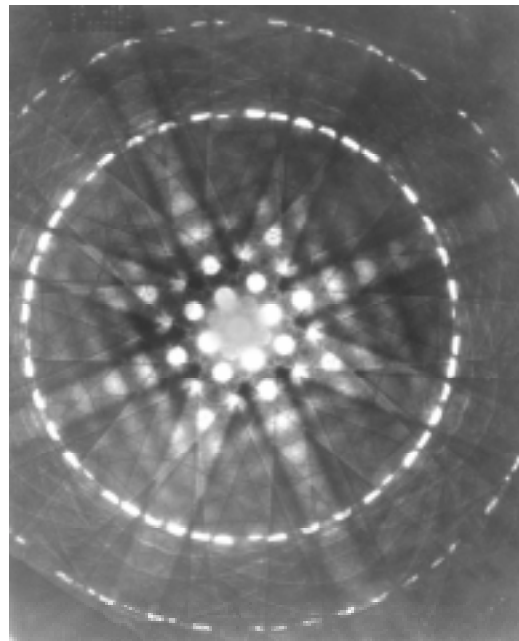


HAADF image, courtesy of A. Bleloch showing higher resolution and chemical sensitivity

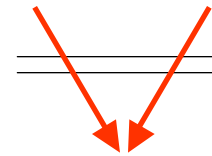
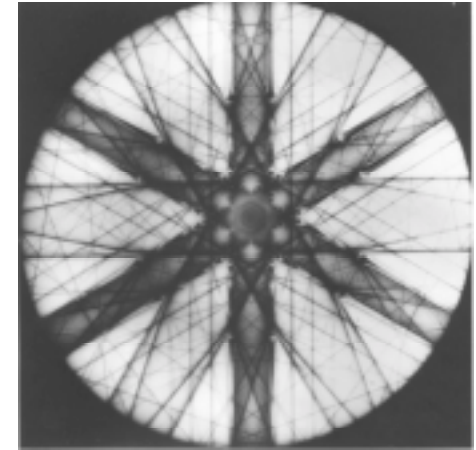
Convergent beam electron diffraction



Selected area
diffraction

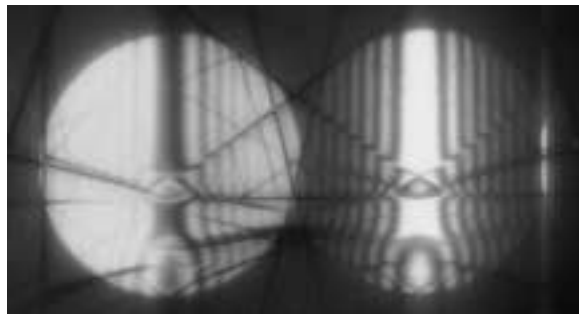
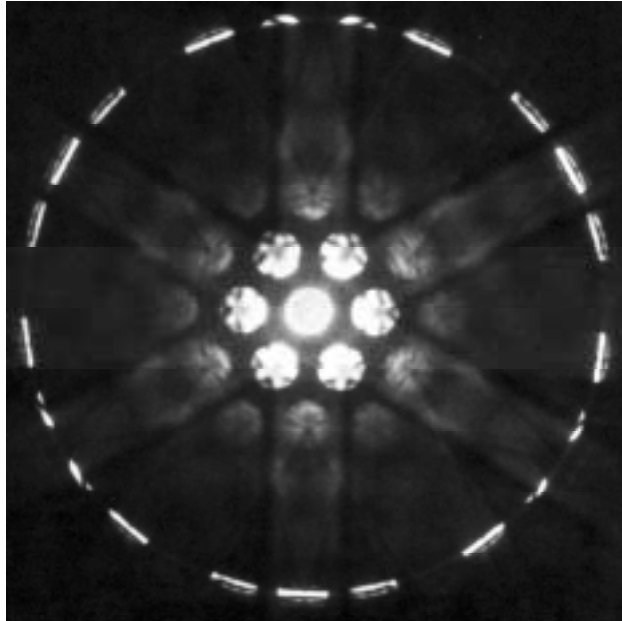


CBED

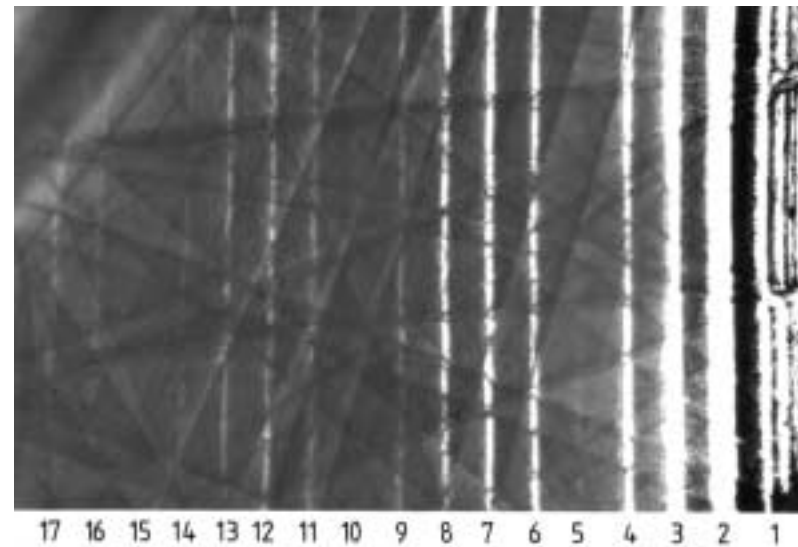
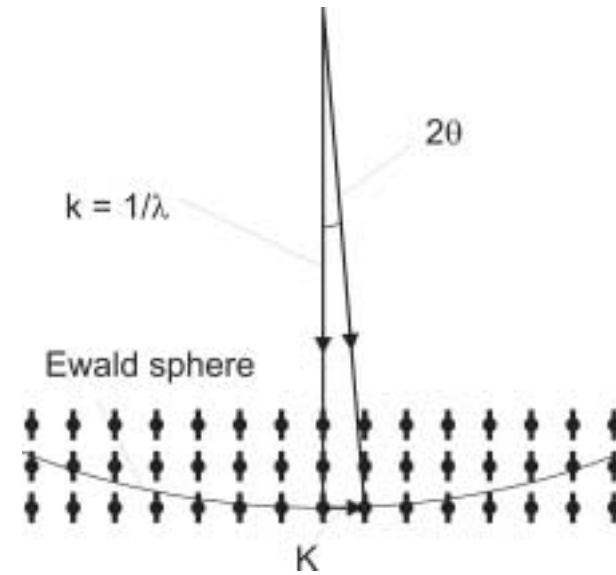


LACBED

Electron rocking curves

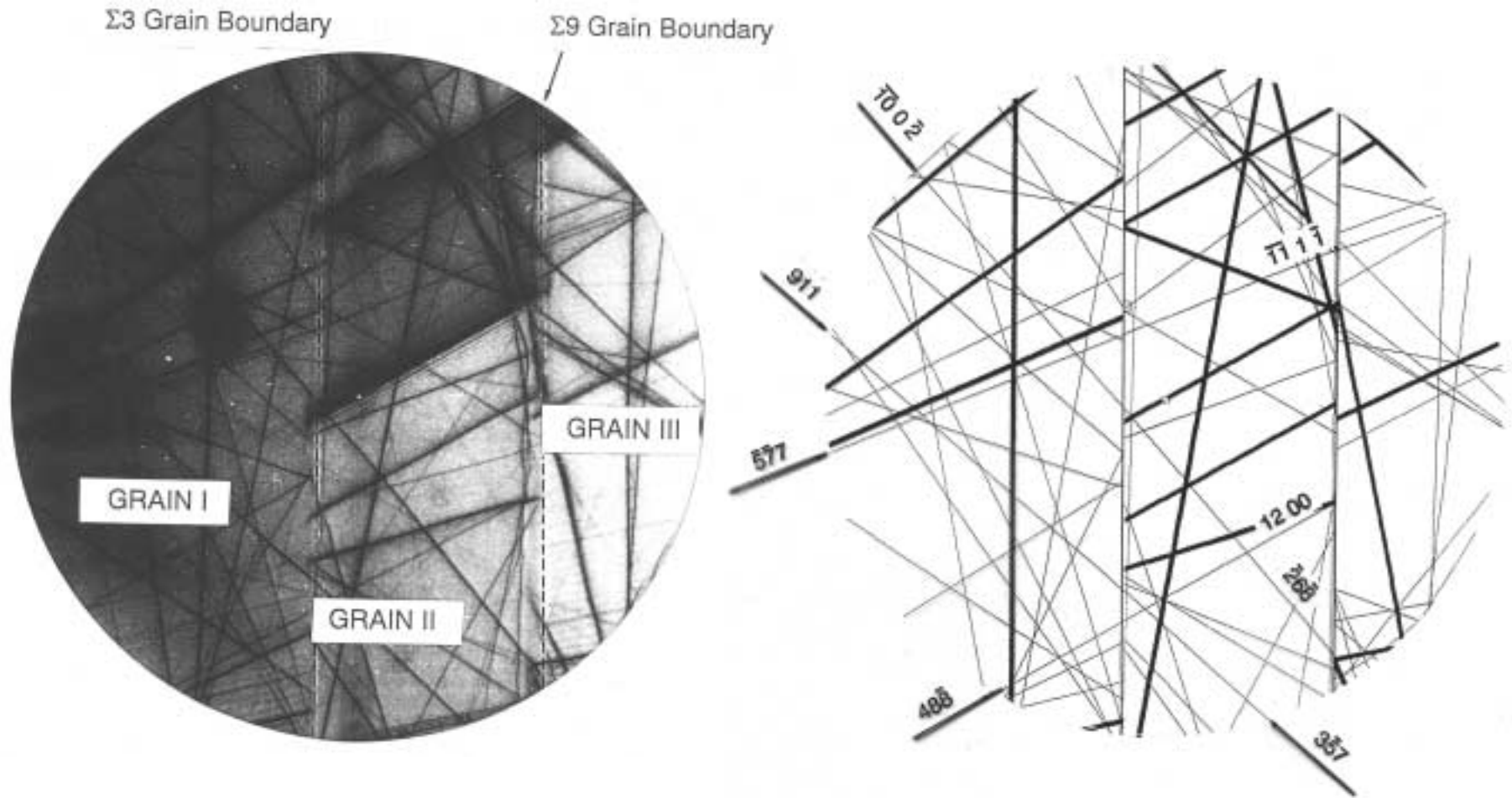


CBED Si 220



LACBED InP/InGaAs MQW 200 disc (Vincent et al Inst Phys Conf Ser 90, 233 (1987))

High order (weak) reflections: grain boundaries in Si

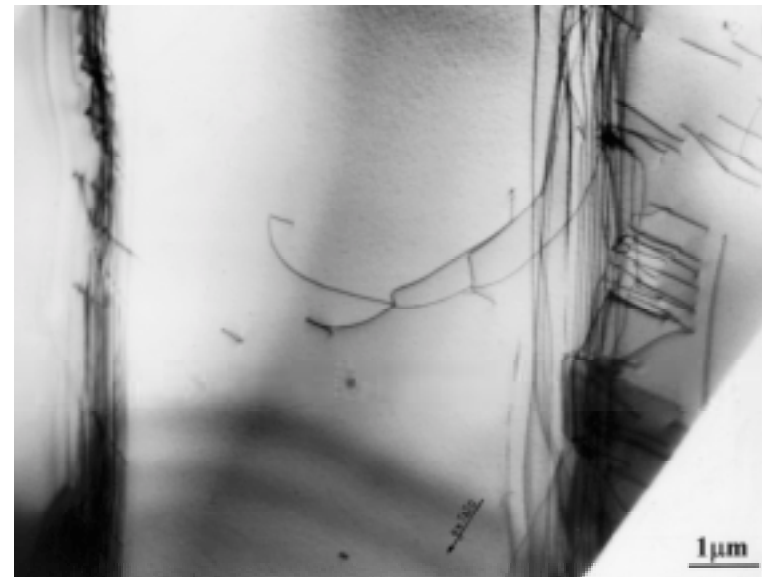
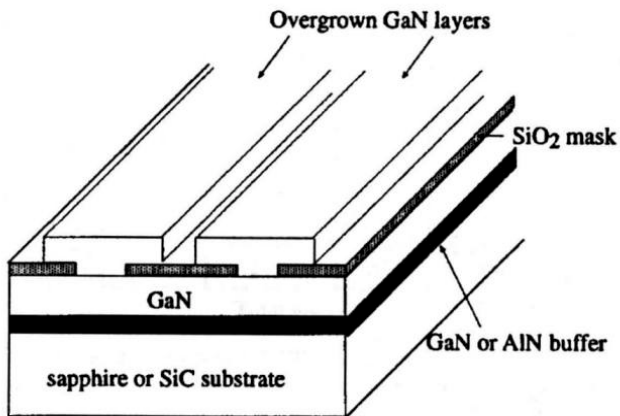
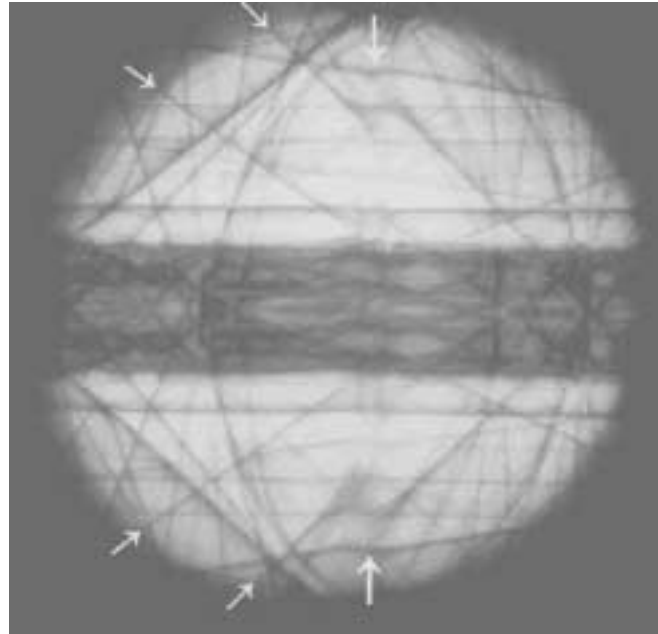


J-P Morniroli and D. Cherns, Ultramicroscopy **62**, 53 (1996)

High order reflections:

Rotation of wings in
GaN ELOG structures

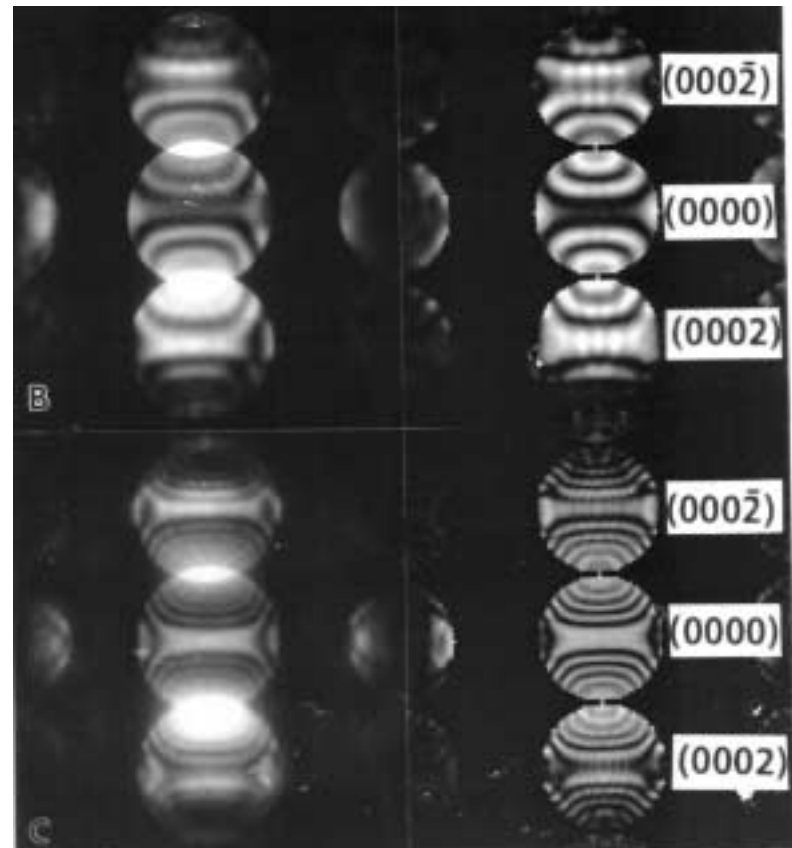
Z Liliental-Weber and
D Cherns JAP **89** 7833
(2001)



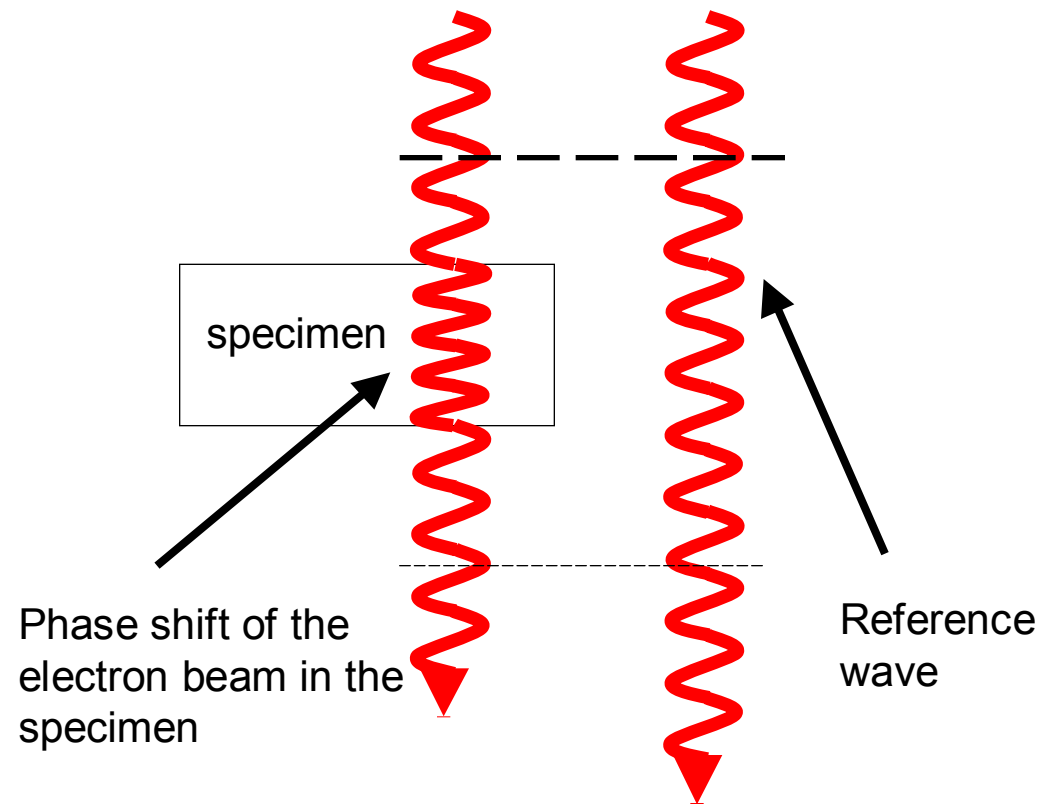
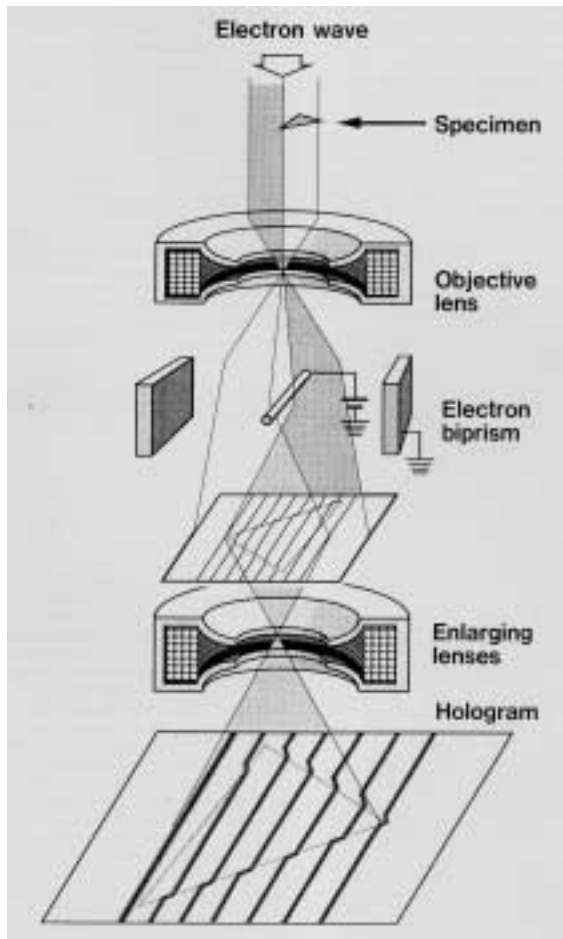
Low order (strong) reflections: polarity determination in GaN/GaN bicrystals



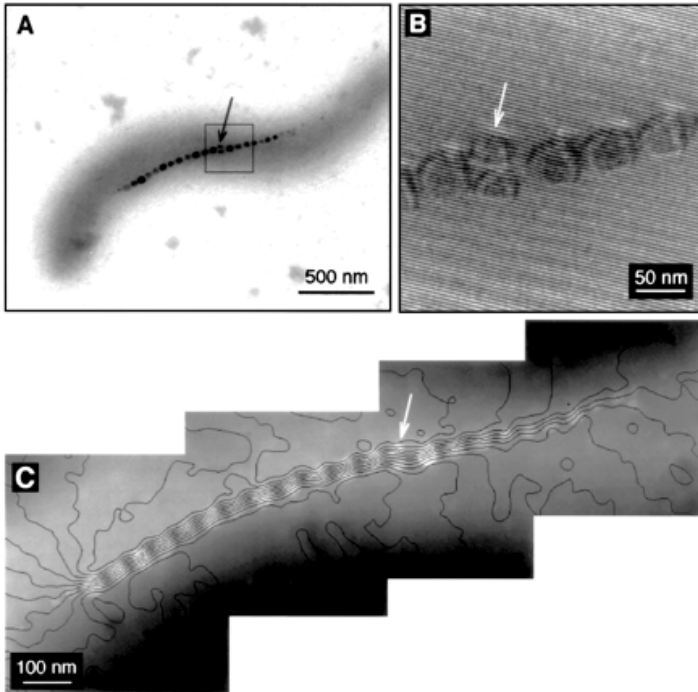
Asymmetry in the CBED patterns is a dynamical effect depending on double diffraction between 0002 and $000\bar{2}$ reflections. It represents breaking of Friedel's Law...



Electron holography



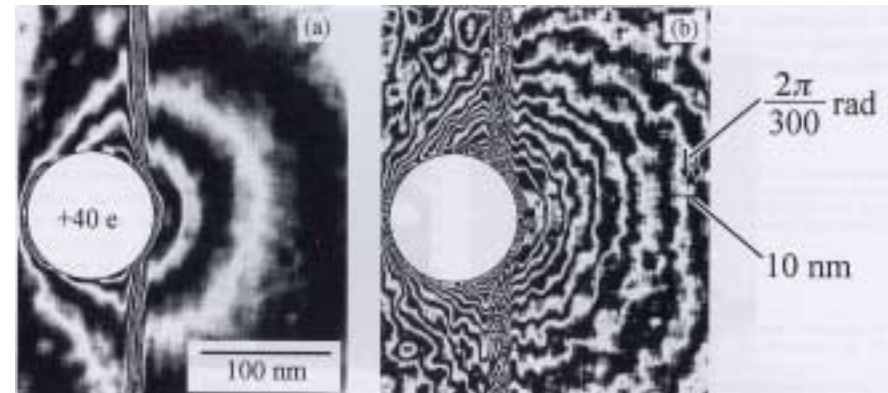
Phase shift depends on the “inner potential”, which can include contributions from internal (and external) magnetic or electric fields

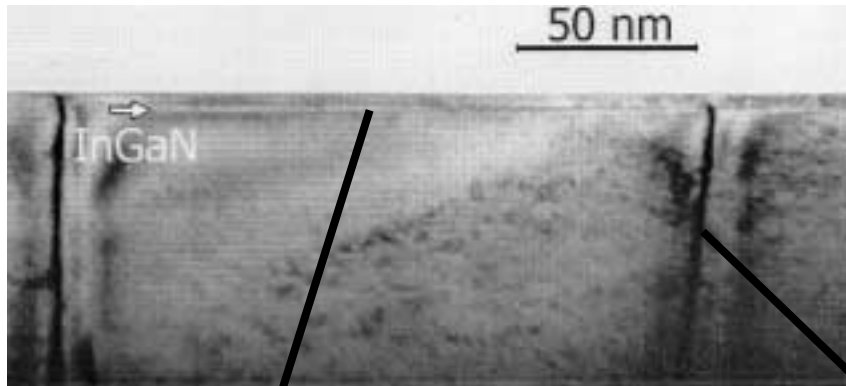


**RE Dunin-Borkowski et al:
electron holography of
magnetotactic bacteria,
Science 282 (1998) 1868**

Examples of holography

**Phase map around a
charged latex sphere (K
Yamamoto et al, JEM 49
(2000) 31)**

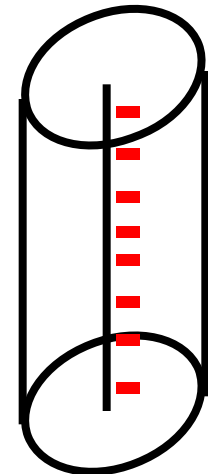
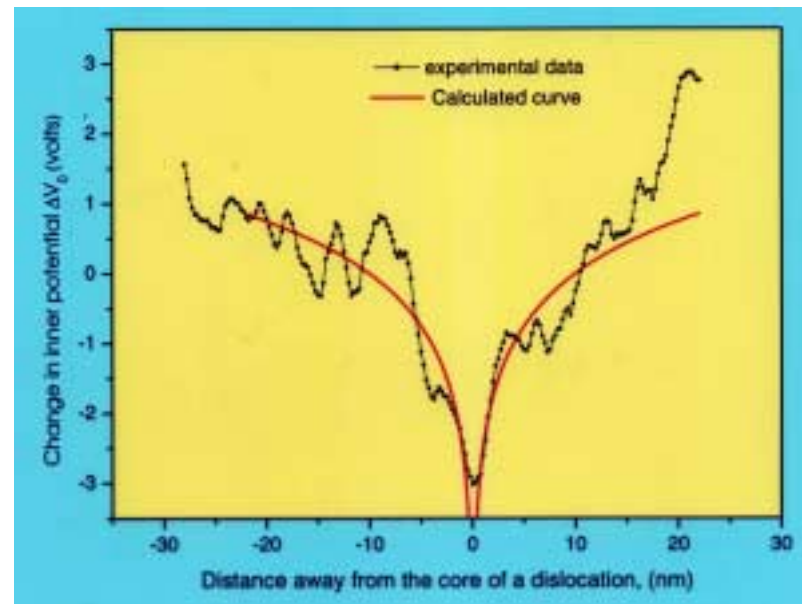




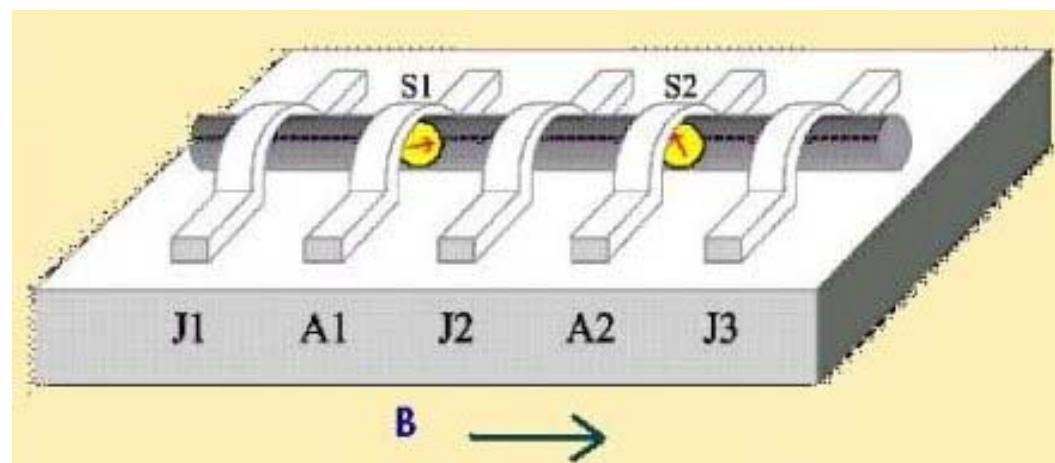
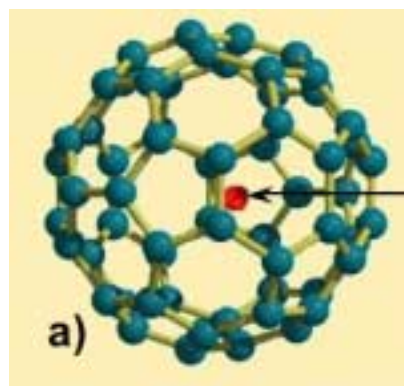
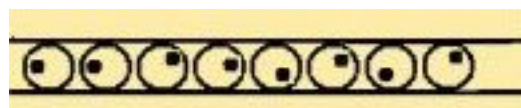
Electric fields in GaN/InGaN LEDs

D. Cherns and C. Jiao
PRL **87**, 205504 (2001)

Cherns, Barnard and Ponce: Solid State Comm. **111**, 281 (1999)



A problem requiring a combination of techniques!



Ref. A Briggs (www.nanotech.org)

Some references and acknowledgements

- P.B. Hirsch et al “Electron Microscopy of Thin Crystals”
- M.H. Loretto “Electron Beam Analysis of Materials”
- D.B. Williams and C.B. Carter “Transmission Electron Microscopy”
- J-P. Morniroli “Large Angle Convergent Beam Electron Diffraction”